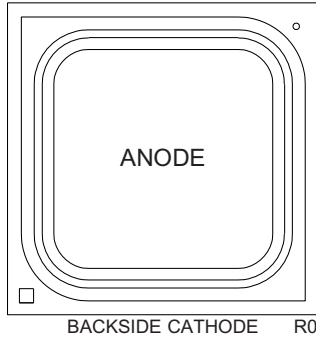


CPD82X-CMDSH2-3

Schottky Diode Die

0.2 Amp, 30 Volt

The CPD82X-CMDSH2-3 is a silicon Schottky diode ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

| | |
|------------------------|------------------|
| Die Size | 14.6 x 14.6 MILS |
| Die Thickness | 5.5 MILS |
| Anode Bonding Pad Size | 11.8 x 11.8 MILS |
| Top Side Metalization | Al – 30,000Å |
| Back Side Metalization | Au – 9,000Å |
| Scribe Alley Width | 1.57 MILS |
| Wafer Diameter | 5 INCHES |
| Gross Die Per Wafer | 80,698 |

MAXIMUM RATINGS: (T_A=25°C)

Peak Repetitive Reverse Voltage

Continuous Forward Current

Peak Forward Surge Current, tp=10ms

Operating and Storage Junction Temperature

SYMBOL

V_{RRM}

I_F

I_{FSM}

T_J, T_{stg}

30

200

1.0

-65 to +150

UNITS

V

mA

A

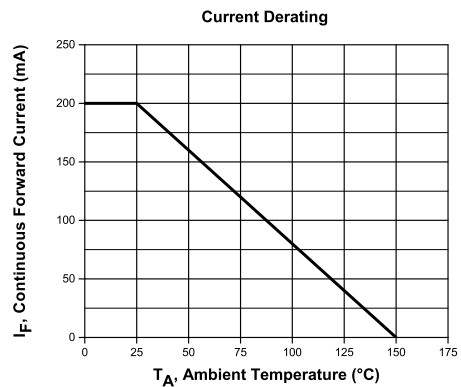
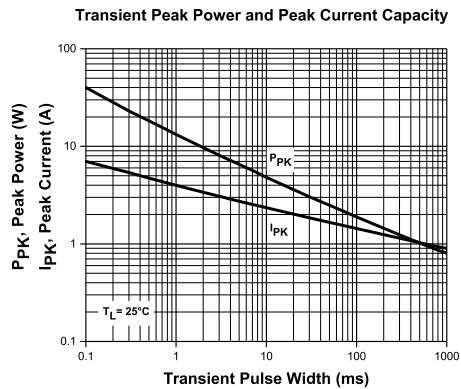
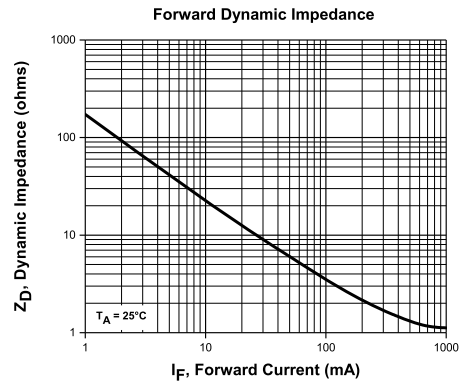
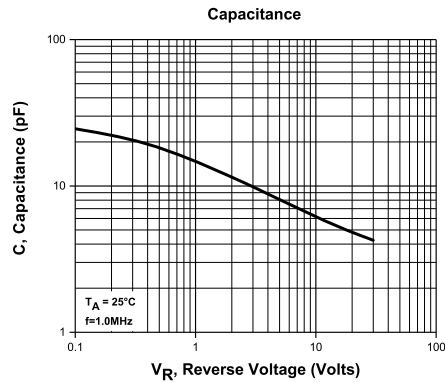
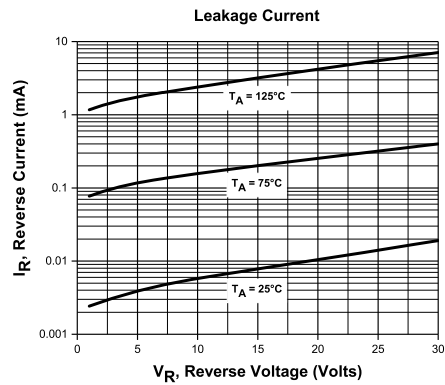
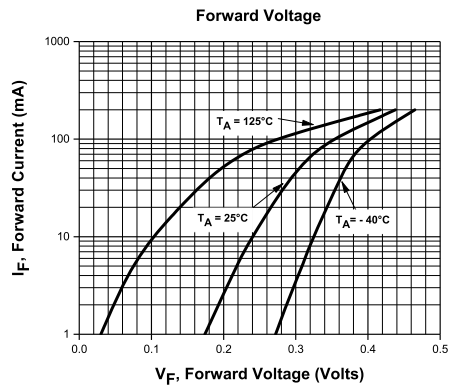
°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C)

| SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|-----------------|-------------------------------|-----|-------|------|-------|
| I _R | V _R =30V | | | 50 | μA |
| BV _R | I _R =100μA | 30 | | | V |
| V _F | I _F =2.0mA | | 0.186 | | V |
| V _F | I _F =15mA | | 0.245 | | V |
| V _F | I _F =100mA | | 0.35 | | V |
| V _F | I _F =200mA | | | 0.55 | V |
| C _J | V _R =10V, f=1.0MHz | | 6.0 | | pF |

CPD82X-CMDSH2-3

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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